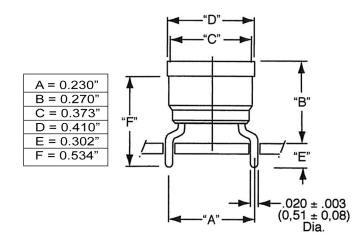
8058 & 8060 Series Transistor Sockets





(SOK) 8058-1G45

(SOK) 8058-6PC



FEATURES:

The 8058/8060 family of teflon sockets, with beryllium copper contacts, offers many features which allow them to be utilized in the most severe applications. Low profile for close board spacing, closed sleeve for 100% prevention of solder and flux wicking. A choice of many terminal styles for greater packaging selection and ease of use. Many of these sockets meet or exceed MIL-S-83502/2 and MIL-S-83502/5.

- Two-piece socket terminal four fingered inner contact and machined outer sleeve
- Low profile for tight space applications
- Sockets accept 0,41/.016 to 0,51/.020 diameter leads
- Printed circuit, solder pocket and turret style terminations available
- Closed entry-design no distortion or damage to contact with misaligned or oversized leads

MATERIAL SPECIFICATIONS:

Insulator	Teflon
Sleeve	Brass
Contact Plating	Beryllium copper
Plating	. Contact gold, sleeve gold

PERFORMANCE SPECIFICATIONS:

MECHANICAL

Vibration
Mechanical Shock Passed MIL-STD -1344, Method 2004, 10 G's,
1 to 9,000 cycles
Durability 50 Insertions and withdrawals,
MIL-S-83502/ 1, Sec. 4.7.12
Insertion Force 4.0 lb. max., .020 dia. +.0000 probe
0002
Withdrawal Force 14 Grams (1/2 oz.) min016 dia. +.0002 probe
0001
Solderability MIL-STD- 202, Method 208
ELECTRICAL
Bulk Contact
Resistance20 Milliohms max. per MIL-S-83502/1
Current Rating3 Amp DC, contact rating
Operating Voltage 500 VDC @ atmospheric pressure
Dielectric Withstanding
Voltage
Insulation Resistance 2 x 106 Megohms, MIL-STD -1344, Method 3003
Capacitance

ENVIRONMENTAL

Operating Temperature .. -55°C to +125°C

Corrosive Atmosphere .. 30 milliohms, ammonium polysulfide 10 ppm per MIL-S-83502/1 Sec. 4.7.17

Moisture Resistance 30 Milliohms max., MIL-STD -202, Method 106

Thermal Shock MIL-STD -1344, Method 1003